

# DB2X415

## Silicon epitaxial planar type

For rectification

### ■ Features

- Low forward voltage  $V_F$
- High forward current (Average) rating :  $I_{F(AV)} = 3\text{ A}$
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

### ■ Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

### ■ Package

- Code  
Mini2-F4-B
- Pin Name  
1: Cathode  
2: Anode

### ■ Marking Symbol: AD

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter                                 | Symbol      | Rating      | Unit             |
|---|-------------|-------------|------------------|
| Reverse voltage                           | $V_R$       | 40          | V                |
| Forward current (Average) *1              | $I_{F(AV)}$ | 3.0         | A                |
| Non-repetitive peak forward surge current | $I_{FSM}$   | 50 *2       | A                |
|   |             | 15 *3       |                  |
| Junction temperature                      | $T_j$       | 125         | $^\circ\text{C}$ |
| Storage temperature                       | $T_{stg}$   | -55 to +125 | $^\circ\text{C}$ |

Note) \*1: Mounted on an alumina PC board

\*2: Rectangle wave 1 cycle (Pulse width = 50 ms, non-repetitive peak current))

\*3: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

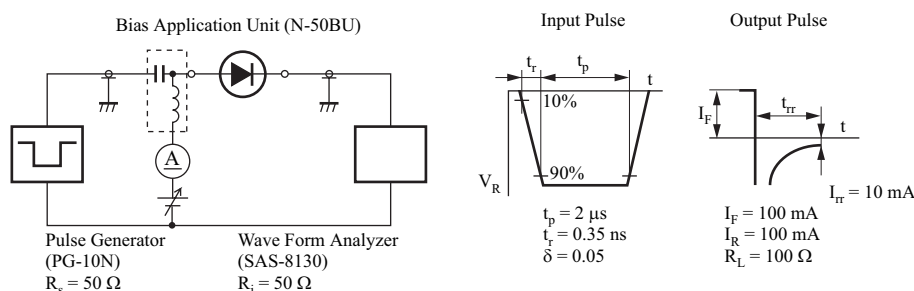
### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

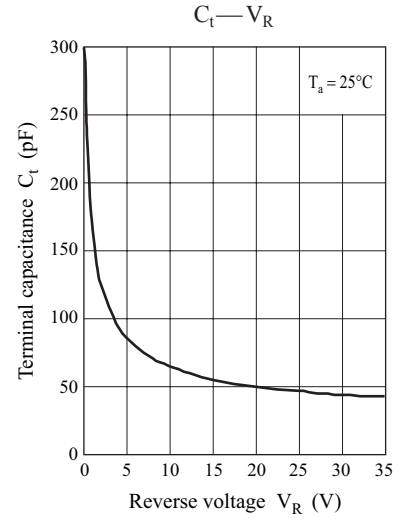
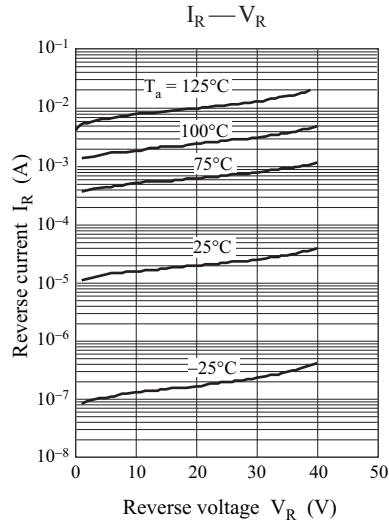
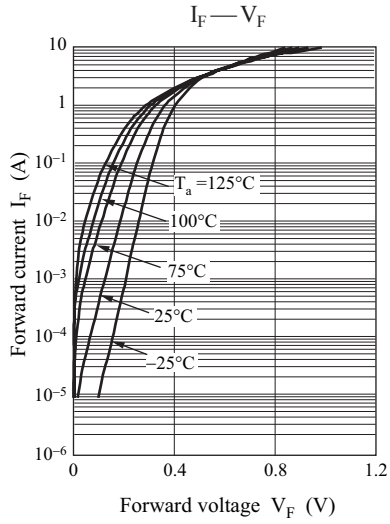
| Parameter               | Symbol   | Conditions  | Min | Typ  | Max  | Unit          |
|-------------------------|----------|---|-----|------|------|---------------|
| Forward voltage         | $V_{F1}$ | $I_F = 1.0\text{ A}$  |     | 0.35 | 0.44 | V             |
|                         | $V_{F2}$ | $I_F = 3.0\text{ A}$  |     | 0.47 | 0.55 |               |
| Reverse current         | $I_R$    | $V_R = 40\text{ V}$   |     | 40   | 200  | $\mu\text{A}$ |
| Terminal capacitance    | $C_t$    | $V_R = 10\text{ V}, f = 1\text{ MHz}$                                 |     | 70   |      | pF            |
| Reverse recovery time * | $t_{rr}$ | $I_F = I_R = 100\text{ mA}, I_{rr} = 10\text{ mA}, R_L = 100\ \Omega$ |     | 25   |      | ns            |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

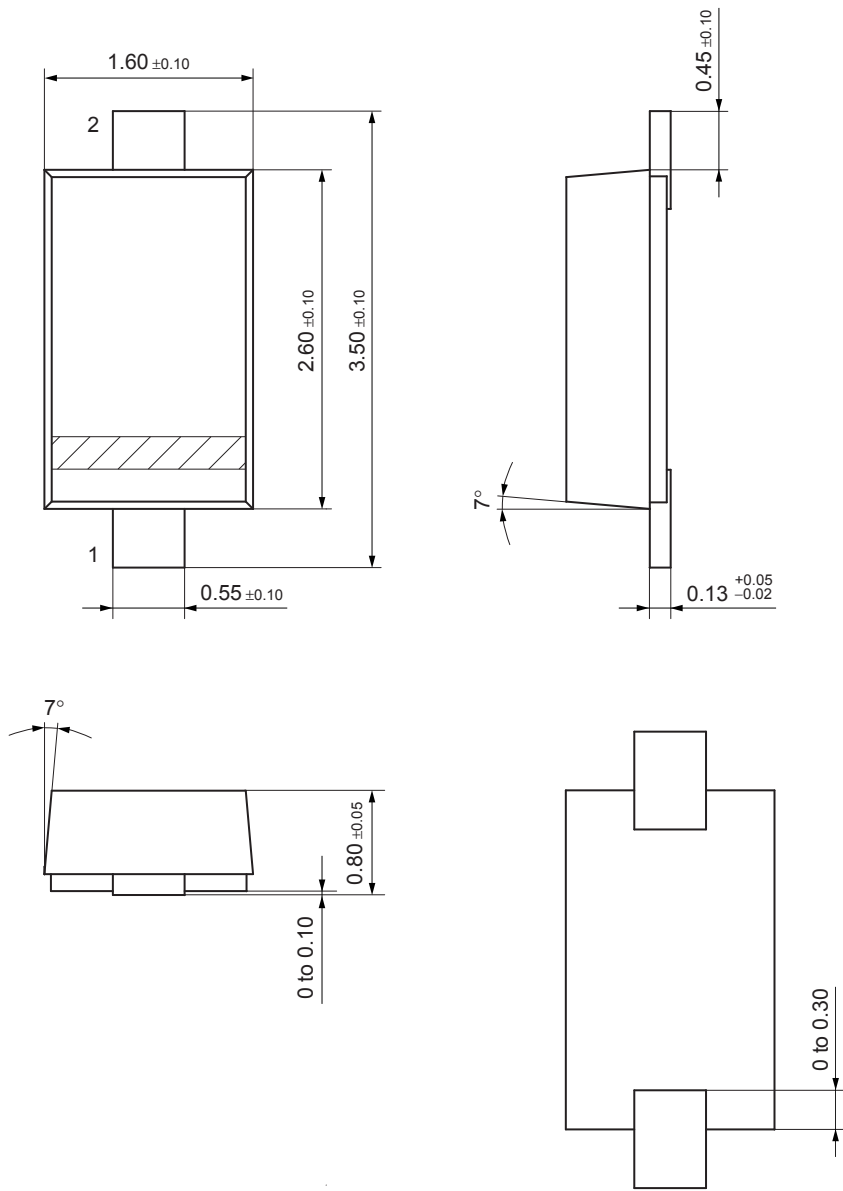
3. \*:  $t_{rr}$  measurement circuit





Mini2-F4-B

Unit: mm



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